

50A 650V Trenchstop Insulated Gate Bipolar Transistor

1 Description

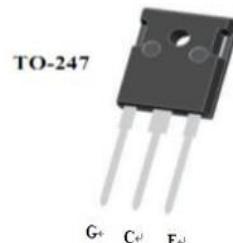
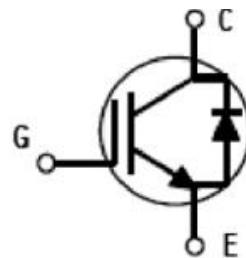
Using DongHai's proprietary Trench design and advance FS technology, the 650V FS IGBT offers superior and switching performances, high avalanche ruggedness easy parallel operation

2 Features

- FS Trench Technology, Positive temperature coefficient
- Low saturation voltage: $V_{CE(sat)}$, typ = 1.8V @ $IC = 50A$ and $T_j = 25^\circ C$
- Extremely enhanced avalanche capability

3 Applications

- Welding
- UPS
- Three-level Inverter



| Type | V_{ce} | I_c | $V_{cesat}, T_j=25^\circ C$ | T_{jmax} | Package |
|------------|----------|-------|-----------------------------|------------|---------|
| G50T65LBBW | 650V | 50A | 1.8V | 175°C | TO-247 |

4 Electrical Characteristics

4.1 Absolute Maximum Ratings ($T_c=25^\circ C$, unless otherwise noted)

| Parameter | | Symbol | Value | Units |
|--|-------------------|-----------|----------|------------|
| Collector-to-Emitter Voltage | | V_{CE} | 650 | V |
| Gate-to-Emitter Voltage | | V_{GE} | ± 20 | V |
| DC Collector current | $T_j=25^\circ C$ | I_c | 100 | A |
| | $T_j=100^\circ C$ | | 50 | A |
| Pulsed Collector Current ⁽¹⁾ | | I_{CM} | 150 | A |
| Diode forward current | $T_j=25^\circ C$ | I_F | 20 | A |
| | $T_j=100^\circ C$ | | 10 | |
| Diode Pulsed Current | | I_{FM} | 40 | A |
| Short circuit withstand time, $V_{GE}=15V$, $V_{cc}=400V$, $T_j=150^\circ C$ | | T_{sc} | 6 | μs |
| Power Dissipation | $T_j=25^\circ C$ | P_{tot} | 417 | W |
| | $T_j=100^\circ C$ | | 208 | W |
| Junction Temperature Range | | T_j | -55~175 | $^\circ C$ |
| Storage Temperature Range | | T_{stg} | -55~150 | $^\circ C$ |
| Soldering temperature | | T_L | 260 | $^\circ C$ |

4.2 Thermal Characteristics

| Parameter | Symbol | Rating | Units |
|---|------------|--------|-------|
| IGBT Thermal Resistance,Junction to Case-sink | R_{thJC} | 0.36 | °C/W |
| IGBT Thermal Resistance,Junction to Ambient | R_{thJA} | 32.58 | °C/W |

4.3 Electrical Characteristics (Tj=25°C,unless otherwise noted)

| Parameter | Symbol | Test Condition | Value | | | Units |
|--|--------------|---|-------|------|------|-------|
| | | | Min | Typ | Max | |
| Off Characteristics | | | | | | |
| Collector-to-Emitter Breakdown Voltage | V_{ce} | $I_c=1\text{mA}, V_{ge}=0\text{V}$ | 650 | -- | -- | V |
| Collector-to-Emitter Leakage Current | I_{ces} | $V_{ce}=650\text{V}, V_{ge}=0\text{V}$ | -- | -- | 1 | μA |
| Gate-to-Emitter Leakage Current | I_{ges} | $V_{ge}=\pm 20\text{V}, V_{ce}=0\text{V}$ | -- | -- | ±100 | nA |
| On Characteristics | | | | | | |
| Gate Threshold Voltage | $V_{ge(th)}$ | $V_{ce}=V_{ge}, I_c=1\text{mA}$ | 5 | 6 | 7 | V |
| Collector-emitter saturation voltage | V_{cesat} | $V_{ge}=15\text{V}, I_c=50\text{A}$ | -- | 1.8 | 2.0 | V |
| Dynamic Characteristics | | | | | | |
| Input Capacitance | C_{iss} | $V_{ce}=30\text{V}, V_{ge}=0\text{V} f=1\text{MHz}$ | -- | 3248 | -- | pF |
| Output Capacitance | C_{oss} | | -- | 134 | -- | |
| Reverse Transfer Capacitance | C_{rss} | | -- | 33 | -- | |
| Switching Characteristics | | | | | | |
| Turn-on delay time | $td(on)$ | $V_{ce}=400\text{V}, I_c=50\text{A}, R_g=10\Omega, V_{ge}=15\text{V},$ 感性负载,Tj=25°C | -- | 36 | -- | nS |
| Rise time | tr | | -- | 102 | -- | nS |
| Turn-off delay time | $td(off)$ | | -- | 94 | -- | nS |
| Fall time | tf | | -- | 72 | -- | nS |
| Turn-on energy | Eon | | -- | 1.55 | -- | mJ |
| Turn-off energy | Eoff | | -- | 1.09 | -- | mJ |
| Total switching energy | Ets | | -- | 2.64 | -- | mJ |
| Turn-on delay time | $td(on)$ | $V_{ce}=400\text{V}, I_c=50\text{A}, R_g=10\Omega, V_{ge}=15\text{V},$ 感性负载,Tj=150°C | -- | 34 | -- | nS |
| Rise time | tr | | -- | 104 | -- | nS |
| Turn-off delay time | $td(off)$ | | -- | 96 | -- | nS |
| Fall time | tf | | -- | 120 | -- | nS |
| Turn-on energy | Eon | | -- | 1.73 | -- | mJ |
| Turn-off energy | Eoff | | -- | 1.2 | -- | mJ |
| Total switching energy | Ets | | -- | 2.93 | -- | mJ |
| Gate charge | Qg | $V_{ce}=400\text{V}, I_c=50\text{A}, V_{ge}=15\text{V}$ | -- | 104 | -- | nC |

Diode Characteristic

| | | | | | | |
|-------------------------------------|-----------|-----------|----|-----|-----|------|
| Diode forward voltage | V_F | $I_F=20A$ | -- | 1.6 | 1.8 | V |
| | | $I_F=40A$ | -- | 1.9 | 2.3 | V |
| Diode reverse recovery time | t_{rr} | | -- | 43 | -- | nS |
| Diode peak reverse recovery current | I_{rrm} | | -- | 3.1 | -- | A |
| Diode reverse recovery charge | Q_{rr} | | -- | 73 | -- | nC |

Notes:

1.Pulse duration is limited by $T_{j,max}$

5 Typical Characteristic Curves

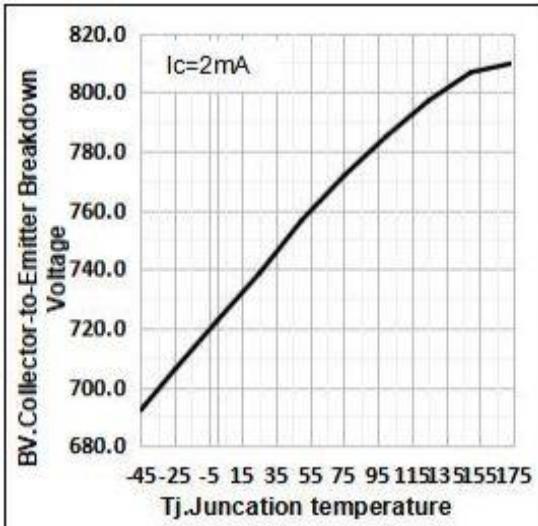


Fig1.Collector-to-Emitter Breakdown Voltage
Temperature characteristic

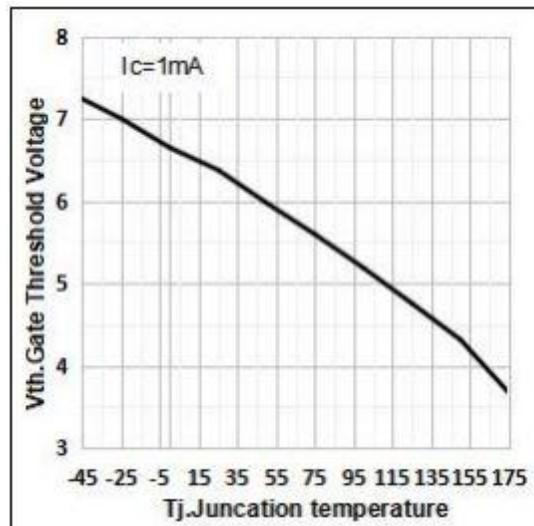


Fig2.Gate Threshold Voltage Temperature
characteristic

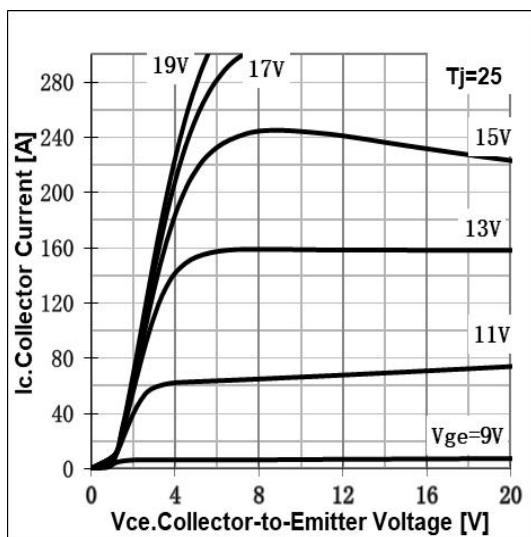


Fig3.Typical output characteristic

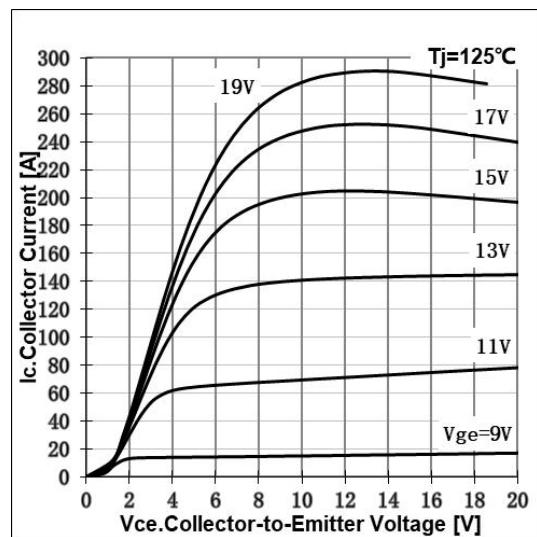


Fig4.Typical output characteristic

5 Typical Characteristic Curves(Continue)

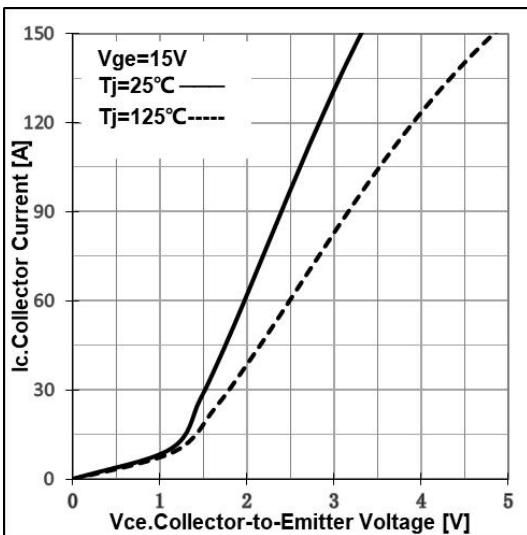


Fig5.Collector-emitter saturation voltage
Characteristic

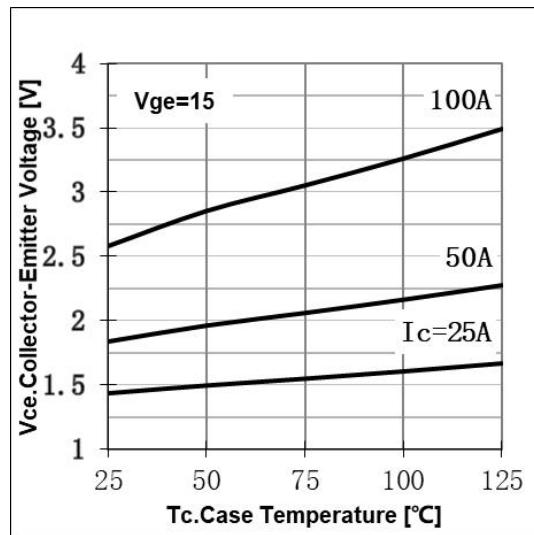


Fig6.Collector-emitter saturation voltage
Temperature Characteristic

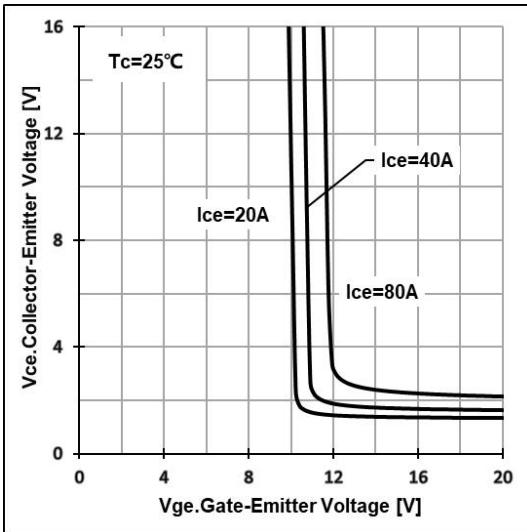


Fig7.Typical Transfer characteristic curve of
Saturation Voltage vs V_{ge}

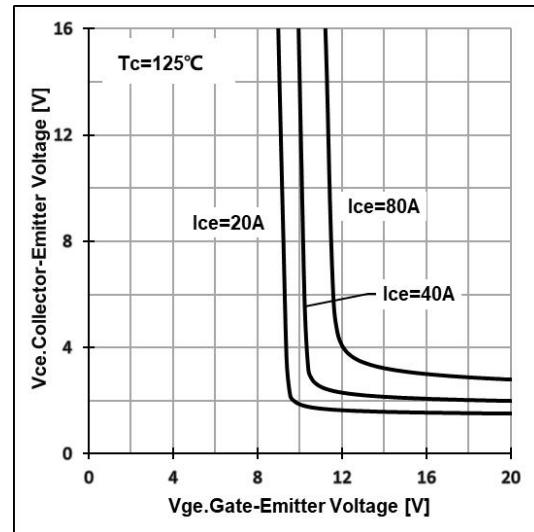


Fig8. Typical Transfer characteristic curve of
Saturation Voltage vs V_{ge}

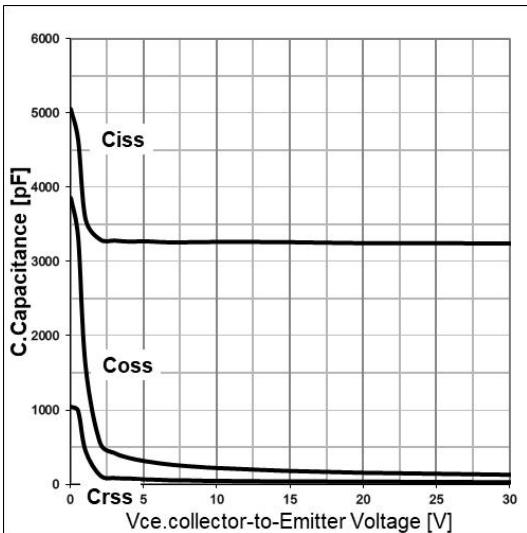


Fig9.Typical capacitance as a function of
collector-emitter voltage

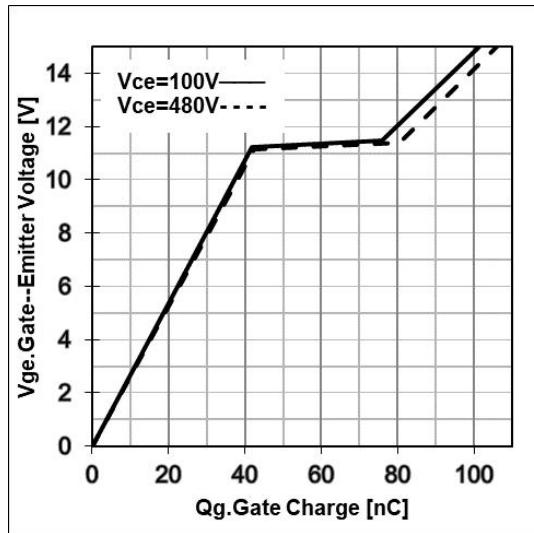


Fig10.Typical gate charge

5 Typical Characteristic Curves(Continue)

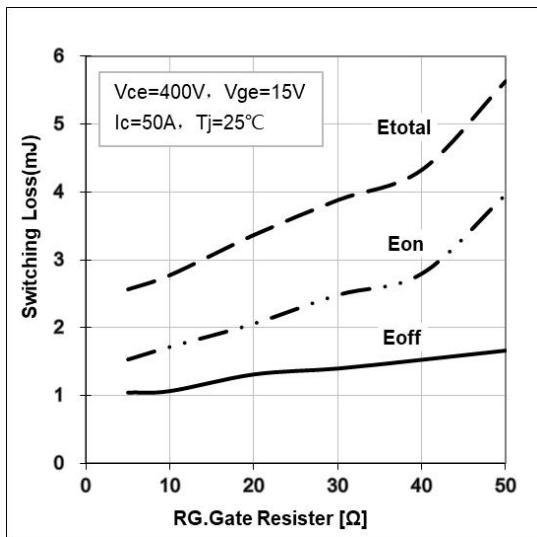


Fig11.Typical switching energy losses as a function of gate resistor

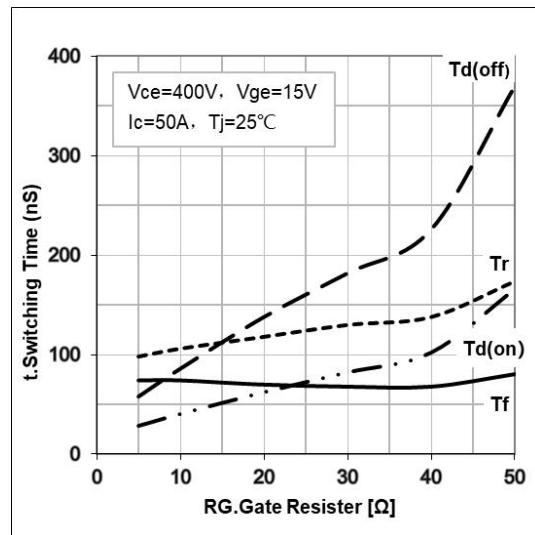


Fig12.Typical switching times as a function of gate resistor

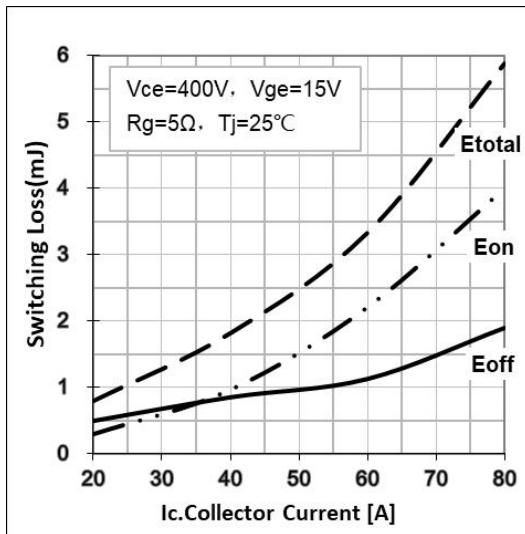


Fig13.Typical switching energy losses as a function of Collector Current

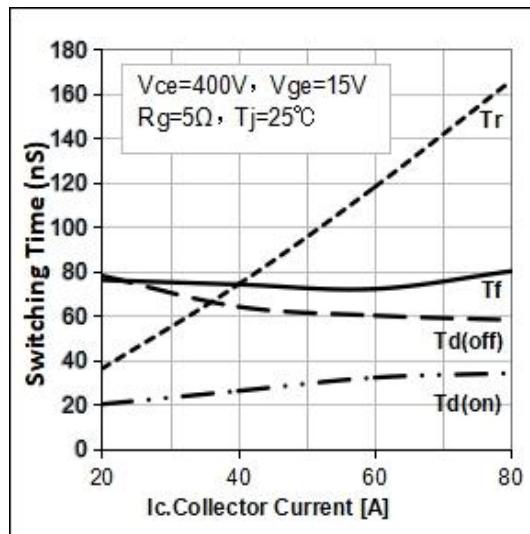


Fig14.Typical switching times as a function of Collector Current

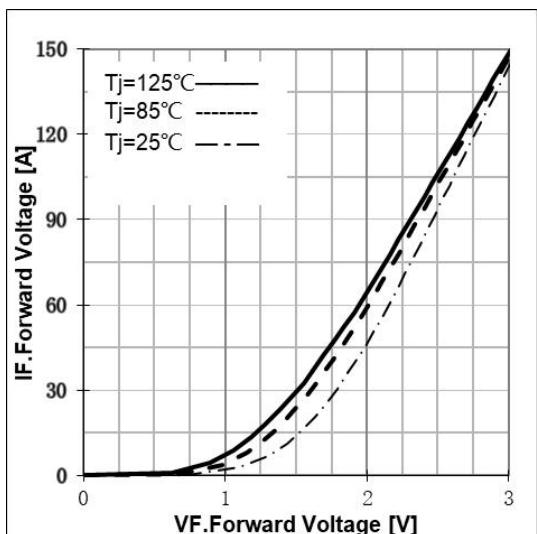


Fig15.Typical diode forward current as a function of forward voltage

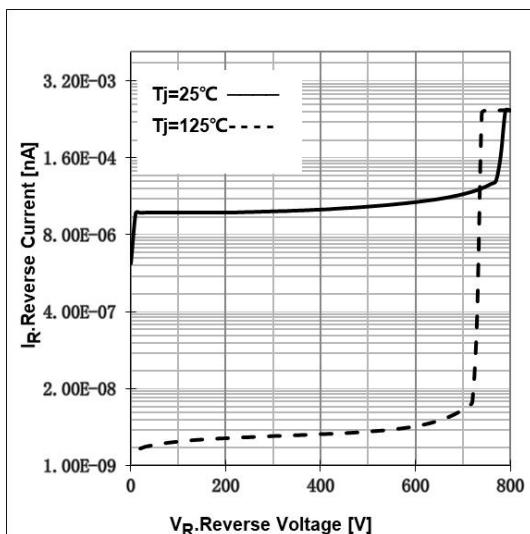


Fig16. Typical diode reverse current as a function of Reverse Voltage

5 Typical Characteristic Curves(Continue)

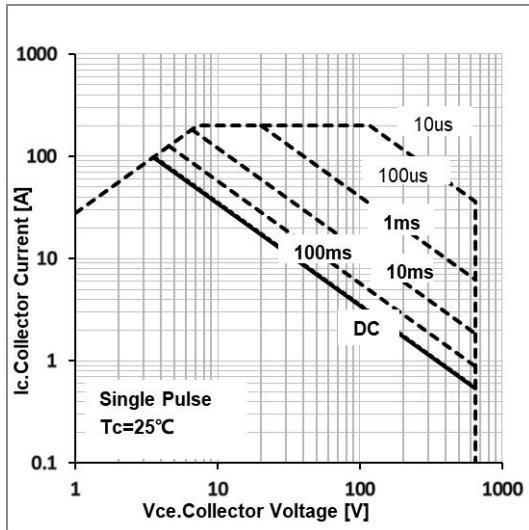


Fig17. Forward bias safe operating area

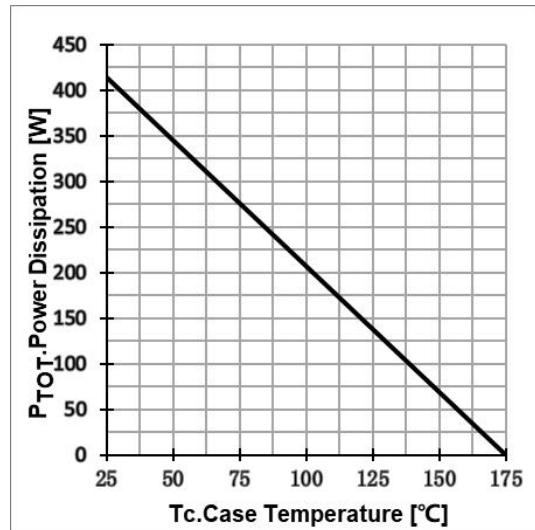


Fig18. Power dissipation temperature characteristic

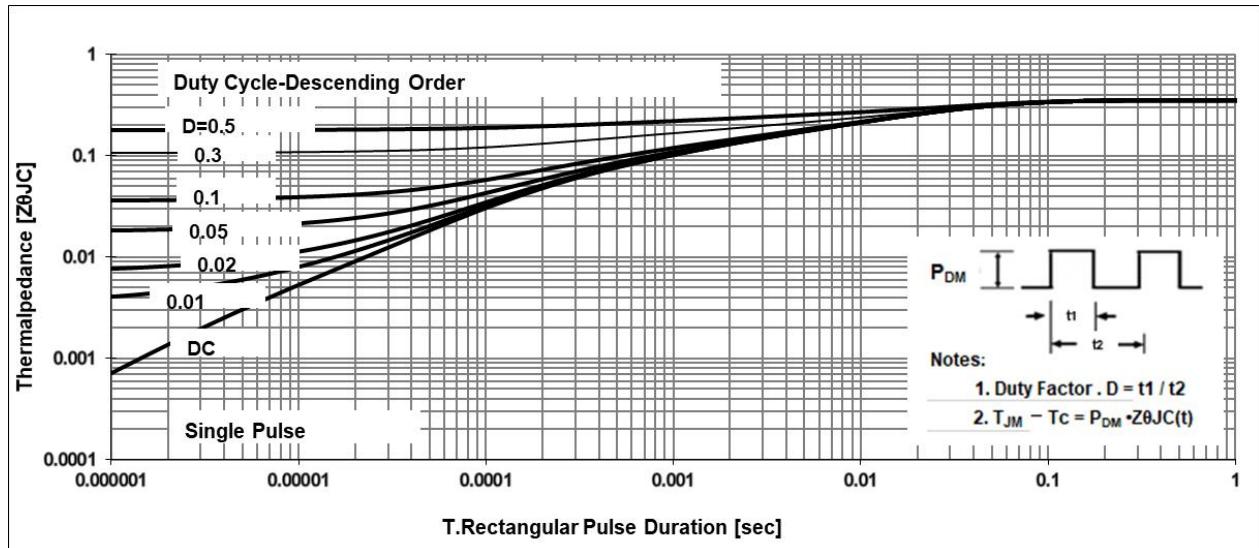
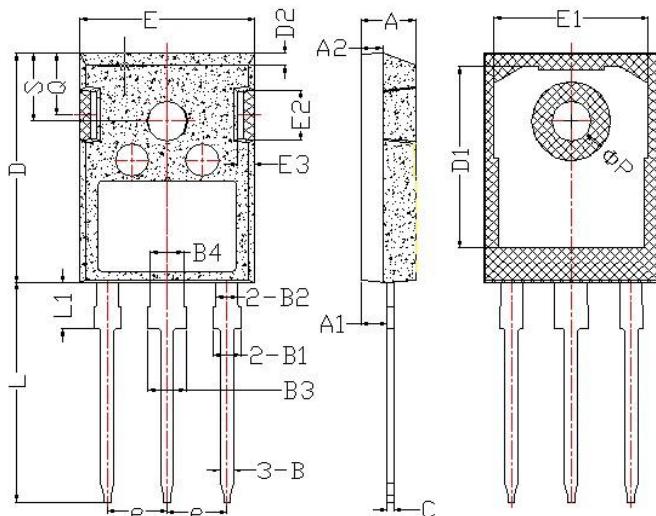


Fig19. IGBT transient thermal resistance

6 Dimensions (TO-247)



| 项 目 | 规范(mm) | | 项 目 | 规范(mm) | |
|-----------|--------------|--------------|-----------|--------------|--------------|
| | MIN | MAX | | MIN | MAX |
| A | 4.60 | 5.20 | E | 15.50 | 16.10 |
| A1 | 2.20 | 2.60 | E1 | 13.00 | 14.70 |
| B | 0.90 | 1.40 | E2 | 3.80 | 5.30 |
| B1 | 1.75 | 2.35 | E3 | 0.80 | 2.60 |
| B2 | 1.75 | 2.15 | e | 5.20 | 5.70 |
| B3 | 2.80 | 3.35 | L | 19.00 | 20.50 |
| B4 | 2.80 | 3.15 | L1 | 3.90 | 4.60 |
| C | 0.50 | 0.70 | ΦP | 3.30 | 3.70 |
| D | 20.60 | 21.30 | Q | 5.20 | 6.00 |
| D1 | 16.00 | 18.00 | S | 5.80 | 6.60 |

7 Atentions

- Jiangsu Donghai Semiconductor Technology CO.,LTD. reserves the right to change the specification without prior notice! The customer should obtain the latest version of the information before making the order and verify that the information is complete and up to date.
- It is the responsibility of the purchaser for any failure or failure of any semiconductor product under certain conditions. It is the responsibility of the purchaser to comply with safety standards and to take safety measures in the system design and machine manufacturing of Donghai products in order to avoid potential risk of failure. Injury or property damage.
- Product promotion is endless, our company will be dedicated to provide customers with better products.

8 Appendix

Revision history:

| Date | REV. | Description | Page |
|------------|------|-------------|------|
| 2021.06.02 | 1.0 | Original | |